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## **NDS0610**

### P-Channel Enhancement Mode Field Effect Transistor

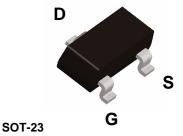
#### **General Description**

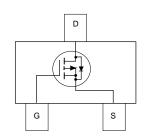
These P-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process has been designed to minimize onstate resistance, provide rugged and reliable performance and fast switching. They can be used, with a minimum of effort, in most applications requiring up to 120mA DC and can deliver current up to 1A.

This product is particularly suited to low voltage applications requiring a low current high side switch.

#### **Features**

- -0.12A, -60V.  $R_{DS(ON)} = 10 \Omega @ V_{GS} = -10 V$   $R_{DS(ON)} = 20 \Omega @ V_{GS} = -4.5 V$
- · Voltage controlled p-channel small signal switch
- High density cell design for low R<sub>DS(ON)</sub>
- High saturation current





#### Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V <sub>DSS</sub>	Drain-Source Voltage	-60	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current - Continuous (Note 1)	-0.12	Α
	– Pulsed	-1	
P <sub>D</sub>	Maximum Power Dissipation (Note 1)	0.36	W
	Derate Above 25°C	2.9	mW/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C
TL	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	300	°C

#### **Thermal Characteristics**

R <sub>eJA</sub> Thermal Resistance, Junction-to-Ambient	(Note 1)	350	°C/W
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**Package Marking and Ordering Information** 

Device Marking	Device	Reel Size	Tape width	Quantity
610	NDS0610	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = -10 \mu\text{A}$	-60			V
<u>ΔBV<sub>DSS</sub></u> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = -10 \mu A$ , Referenced to 25°C		-53		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -48 \text{ V},  V_{GS} = 0 \text{ V}$			-1	μΑ
		V <sub>DS</sub> = -48 V,V <sub>GS</sub> = 0 V T <sub>J</sub> = 125°C			-200	μΑ
I <sub>GSS</sub>	Gate-Body Leakage.	$V_{GS} = \pm 20 \text{ V},  V_{DS} = 0 \text{ V}$			±10	nA
On Chara	acteristics (Note 2)					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = -1 \text{ mA}$	-1	-1.7	-3.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I <sub>D</sub> = −1 mA,Referenced to 25°C		3		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	$V_{GS} = -10 \text{ V},  I_D = -0.5 \text{ A}$ $V_{GS} = -4.5 \text{ V},  I_D = -0.25 \text{ A}$ $V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}, T_J = 125^{\circ}\text{C}$		1.0 1.3 1.7	10 20 16	Ω
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS} = -10 \text{ V},  V_{DS} = -10 \text{ V}$	-0.6			Α
<b>g</b> <sub>FS</sub>	Forward Transconductance	$V_{DS} = -10V$ , $I_{D} = -0.1 \text{ A}$	70	430		mS
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -25 \text{ V},  V_{GS} = 0 \text{ V},$		79		pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		10		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			4		pF
$R_{\text{G}}$	Gate Resistance	$V_{GS} = -15 \text{ mV}, f = 1.0 \text{ MHz}$		10		Ω
Switchin	g Characteristics (Note 2)					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = -25 \text{ V},  I_D = -0.12 \text{ A},$		2.5	5	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = -10 \text{ V},  R_{GEN} = 6 \Omega$		6.3	12.6	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			10	15	ns
t <sub>f</sub>	Turn-Off Fall Time			7.5	15	ns
$Q_g$	Total Gate Charge	$V_{DS} = -48 \text{ V},  I_{D} = -0.5 \text{ A},$		1.8	2.5	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = -10 V		0.3		nC
$Q_{gd}$	Gate-Drain Charge			0.4		nC
Drain-Sc	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain-Source				-0.24	Α
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{S} = -0.24 \text{ A(Note 2)}$		-0.8	-1.5	V
t <sub>rr</sub>	Diode Reverse Recovery Time	$I_F = -0.5A$		17		nS
Q <sub>rr</sub>	Diode Reverse Recovery Charge	$d_{iF}/d_t = 100 \text{ A/}\mu\text{s}$ (Note 2)		15		nC

#### Notes

1.  $R_{\theta,JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta,JC}$  is guaranteed by design while  $R_{\theta,CA}$  is determined by the user's board design.



a) 350°C/W when mounted on a minimum pad..

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%

## **Typical Characteristics**

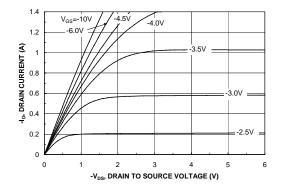


Figure 1. On-Region Characteristics.

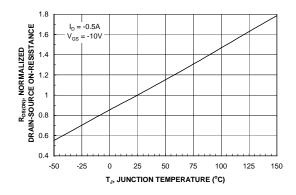


Figure 3. On-Resistance Variation with Temperature.

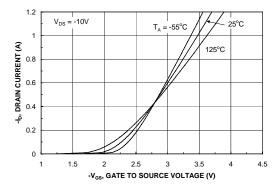


Figure 5. Transfer Characteristics.

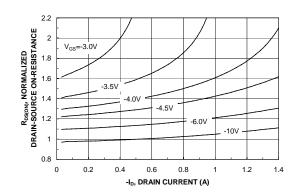


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

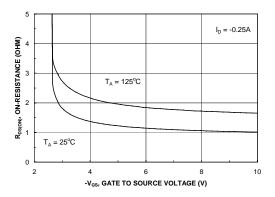


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

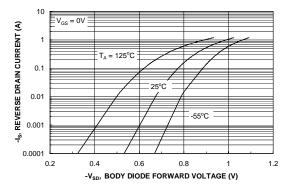
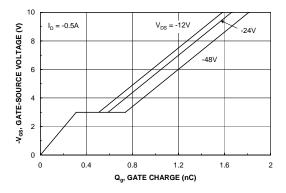


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## **Typical Characteristics**



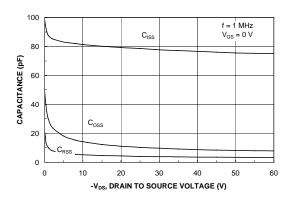


Figure 7. Gate Charge Characteristics.

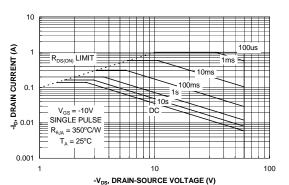


Figure 8. Capacitance Characteristics.

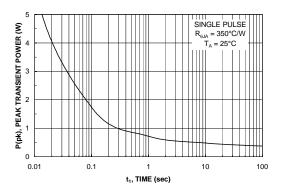


Figure 9. Maximum Safe Operating Area.



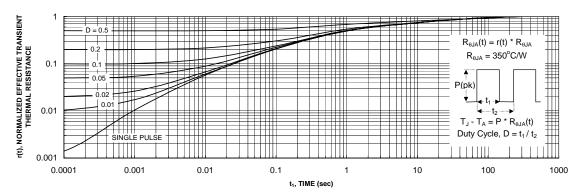


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1a. Transient thermal response will change depending on the circuit board design.

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